

Appln. No. 10/532,949
Response dated June 19, 2008 to
Reply to Office Action of March 28, 2008

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Amendments to the Claims:

Please amend claims 1, 2, 6 and 7 as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently Amended). A jig for holding and conveyance comprising:

a plate having a weak-adherence adhesive pattern on [[its]] a surface of the plate; and

5 a printed circuit board having a conductive portion and a non-conductive portion on [[its]] a surface of the printed circuit board, or a conductive material laminated plate for manufacturing said printed circuit board, said printed circuit board or said conductive material laminated plate being placed
10 and held on the surface of said plate,

wherein said weak-adherence adhesive pattern is formed at a position corresponding to said non-conductive portion.

Claim 2 (Currently Amended). A jig for holding and conveyance comprising:

a plate having a weak-adherence adhesive layer on [[its]] a surface of the plate; and

5 a printed circuit board having a conductive portion and a

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non-conductive portion on [[its]] a surface of the printed
circuit board, or a conductive material laminated plate for
manufacturing said printed circuit board, said printed circuit
board or said conductive material laminated plate being placed
10 and held on the surface of said plate,

wherein a weak-adherence adhesive pattern subjected to
surface roughening is formed on a surface of said weak-adherence
adhesive layer at a position corresponding to said conductive
portion.

Claim 3 (Previously Presented). The jig for holding and
conveyance according to claim 1, wherein said weak-adherence
adhesive pattern has a plurality of thickness regions differing
in thickness from the surface of said plate.

Claim 4 (Previously Presented). The jig for holding and
conveyance according to claim 1, wherein said weak-adherence
adhesive pattern has a plurality of adhesive strength regions
differing in adhesive strength.

Claim 5 (Original). The jig for holding and conveyance
according to claim 2, wherein a non-adhesive pattern is formed at
a position corresponding to said conductive portion on the
surface of said weak-adherence adhesive layer.

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Claim 6 (Currently Amended). A method of conveying a printed circuit board having a conductive portion and a non-conductive portion on [[its]] a surface of the printed circuit board while holding said printed circuit board on a jig for holding and conveyance, said jig having a weak-adherence adhesive pattern provided on [[its]] a surface of the jig, the method comprising the step of:

~~wherein when holding~~ said printed circuit board ~~is held~~ on the surface of said jig for holding and conveyance, in a manner such that said non-conductive portion is placed by being restricted to a surface of said weak-adherence adhesive pattern..

Claim 7 (Currently Amended). A method of conveying an electroconductive material laminated plate for manufacturing a printed circuit board having a conductive portion and a non-conductive portion on [[its]] a surface of the printed circuit board while holding said electroconductive material laminated plate on a jig for holding and conveyance, said jig having a weak-adherence adhesive pattern provided on [[its]] a surface of the jig, the method comprising the step of:

~~wherein when holding~~ said electroconductive material laminated plate ~~is held~~ on the surface of said jig for holding and conveyance, in a manner such that a portion intended for formation of said non-conductive portion is placed by being

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restricted to a surface of said weak-adherence adhesive pattern.

Claim 8 (Withdrawn). A jig for holding and conveyance
comprising:

a plate having a weak-adherence adhesive layer on its
surface;

5 a printed circuit board having a conductor pattern on its
insulating substrate surface, or an electroconductive material
laminated plate for manufacturing said printed circuit board,
said printed circuit board or said electroconductive material
laminated plate being placed and held on the surface of said
10 plate,

wherein said weak-adherence adhesive layer is a
fluorine-based resin layer.

Claim 9 (Withdrawn). The jig for holding and conveyance
according to claim 8, wherein said fluorine-based resin layer is
formed so as to hold said printed circuit board or said
electroconductive material laminated plate so that a surface of
5 said conductor pattern or an electroconductive material foil
surface of said electroconductive material laminated plate is
approximately parallel to the surface of said plate.

Claim 10 (Withdrawn). The jig for holding and conveyance

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according to claim 8, wherein said fluorine-based resin layer has a plurality of thickness regions differing in thickness from the surface of said plate.

Claim 11 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has a plurality of adhesive strength regions differing in adhesive strength.

Claim 12 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein surface roughening is selectively performed on a region of said fluorine-based resin layer other than a holding portion for holding said printed circuit board or
5 said electroconductive material laminated plate.

Claim 13 (Withdrawn). The jig for holding and conveyance according to any one of claim 8, wherein a plurality of said fluorine-based resin layers are provided on the surface of said plate, and a non-adhesive material layer is provided on a
5 non-formation portion of said fluorine-based resin layers on the surface of said plate.

Claim 14 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has

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a holding portion for holding said printed circuit board or said
electroconductive material laminated plate, and has a
5 non-adhesive layer on a portion other than said holding portion.

Claim 15 (Withdrawn). The jig for holding and conveyance
according to claim 8, wherein said fluorine-based resin layer has
a hardness (JIS-A) of 100° or lower.

Claim 16 (Previously Presented). The jig for holding and
conveyance according to claim 2, wherein said weak-adherence
adhesive pattern has a plurality of thickness regions differing
in thickness from the surface of said plate.

Claim 17 (Previously Presented). The jig for holding and
conveyance according to claim 2, wherein said weak-adherence
adhesive pattern has a plurality of adhesive strength regions
differing in adhesive strength.

Claim 18 (Previously Presented). The jig for holding and
conveyance according to claim 3, wherein said weak-adherence
adhesive pattern has a plurality of adhesive strength regions
differing in adhesive strength.

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Claim 19 (Previously Presented). The jig for holding and conveyance according to claim 16, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.